LiPOLY®
SHIU LI TECHNOLOGY CO.,LTD

N800B

Non-Silicone Thermal Conductive Pad

Non-Silicone Thermal Compound N800B is made of non-silicon resin material. No low-molecular-weight siloxane volatilization, no electrical contact & pollution problems. N800B is flexible and has great thermal conduction, making the thermal resistance as low as possible. The thermal conductivity is 13.0W/m*K. It's suitable for optical and sensitive electric components.

FEATURES

/ Thermal conductivity:13.0 W/m*K
/ It's made by non-silicone resin materials
/ Low contact thermal resistance
/ With electrical insulation
/ Outstanding thermal conductivity
/ Applicable to optical and sensitive electric components

TYPICAL APPLICATION

/ HDDS
/ Optical appliance

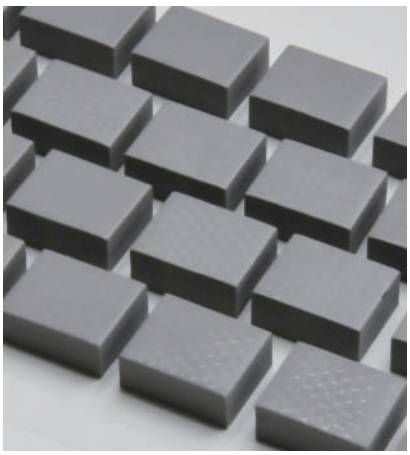
SPECIFICATIONS

/ Sheet form
/ Die-cut parts

TYPICAL PROPERTIES

PROPERTY	N800B	TEST METHOD	UNIT
Color	Gray	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	3.3	ASTM D792	g/cm³
Hardness	50	ASTM D2240	Shore OO
Application temperature	-60~125	-	°C
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	12	ASTM D5470 modify	%
Deflection @20 psi	32	ASTM D5470 modify	%
Deflection @30 psi	63	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	8	ASTM D149	KV/mm
Surface resistivity	$>10^{11}$	ASTM D257	Ohm
Volume resistivity	$>10^{10}$	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	13.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.183	ASTM D5470	°C-in²/ W
Thermal impedance@20 psi	0.131	ASTM D5470	°C-in²/ W
Thermal impedance@30 psi	0.074	ASTM D5470	°C-in²/ W

The chemical formula indicates that if Cyclic polydimethylsilox-ane ($HO-[Si(CH_3)_2O]_n-H$) is non-reaction, it's volatile anytime and everywhere. For example, when the electric products which has been put in a confined space, the volatile of low-molecular-weight silox-anes will makes the elecetic products uncontacted.



Thermal Resistance vs. Pressure vs. Deflection